

Form PTO-1449

INFORMATION DISCLOSURE CITATION
IN AN APPLICATION

(Use several sheets if necessary)

Docket Number (Optional)

IME-03-005

Application Number

10/748,736

Applicant

Wang Ec Hua et al.

Filing Date

12/30/03

Group Art Unit

2813

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	PRIOR DATE IF APPROPRIATE
CC	5251806	10/12/93	Agarwala et al.	228	180.22	4/16/92
CC	5441195	8/15/95	Tustanivskyj et al.	228	180.22	1/13/94
CC	5964396	10/12/99	Brofman et al.	228	180.22	8/12/97
CC	5975409	11/2/99	Brofman et al.	228	180.22	8/12/97
CC	6442831	9/3/02	Khandros et al.	29	843	1/24/97
CC	5790377	8/4/98	Schreiber et al.	361	704	9/12/96

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
					YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

CC	-	Larry Gilg, Die Products Consortium, Austin, TX - FRP, 7/1/02, "Wafer-Level vs. Singulated Die Burn-In and Test"
CC	-	Beth Keser, et al., "Encapsulated Double-Bump WLB-CSP: Design and Reliability," Proc. 51st Electronic Component Tech. Conf. 2001, pp. 35-39.
CC	-	J. Simon, "Development and Board Level Reliability of a Wafer-level CSP," Proc. 41st IEMT/IMC 2000, pp. 22-27.

EXAMINER

Chandra Chaudhari

DATE CONSIDERED

1-05

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

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Wong Ee Hua et al.

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Group 11 Unit

28/3

U. S. PATENT DOCUMENTS

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FOREIGN PATENT DOCUMENTS

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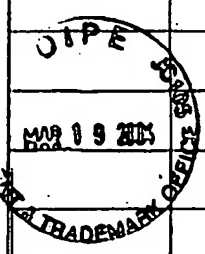
OTHER DOCUMENTS (Including Author, Title, Date, Portion, Pages, Etc.)

CC	-	S.I. Demda, et al., "Wafer Level Packaging Technology in Japan", Proc 4th IEMT/Imc, 2000, pp. 4-9, (Fig. 2).
CC	-	Advanced IC packaging markets and trends, pp. 4-49 to 4-51, Electronic Trend Publication, 6th Edition, 2002.
CC	-	Bakir, et al., "Sea of Leads Ultra High-Density Compliant Wafer-Level Packaging Technology", Proc. 52nd Elec. Component Tech Conf., 2002, pp. 1087-1094.
EXAMINER		DATE CONSIDERED
Chandra Chaudhori		/-05

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	Applicant Wong Ee Hua et al.	
	Filing Date 12/30/03	Group Art Unit 2813

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DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

cc -	P. Garrou, et al., "Cyclotene BCB Resin for Bumping and Water Level Chip Scale Packaging (WL-CSP), Proc. 380
	TEMT/IMC, pp. 206-211, 1999.

EXAMINER Chandra Chaudhari	DATE CONSIDERED 1-05
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